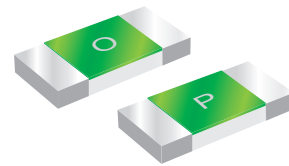


Time Delay | 0.126x0.064 inch Thick Film Chip Fuses

1206TD Series

Features

- High inrush current withstanding capability
- AEC-Q200 Automotive Grade Certified
- Compatible with reflow and wave solder
- Ceramic and glass construction
- Excellent environmental integrity
- One time positive disconnect
- Lead Free and Halogen free material



Electrical Characteristics

Amp Rating	% of Amp Rating	Opening Time
0.63~50A	100%	4 Hours Min.
0.63~3A	200%	1sec~60sec
0.63~5A	250%	5 Seconds Max.
0.63~5A	300%	0.1sec~3sec
6~50A	350%	5 Seconds Max.
0.63~50A	1000%	0.2ms~20ms

Specification

Part Number	Ampere Rating (A)	Interrupting Rating	Voltage Rating	Typical Cold Resistance (Ohms)	Typical Melting I ² t (A ² Sec)	Typical Voltage Drop (V)	Marking Code
1206TD-R630	0.63	50A @ 72Vdc 50A @ 63Vdc		1.08	0.009	0.950	B
1206TD-R750	0.75			0.85	0.01	0.900	0.75
1206TD-1A	1.00			0.48	0.11	0.510	H
1206TD-1.25A	1.25			0.33	0.15	0.500	H
1206TD-1.5A	1.50			0.23	0.17	0.465	K
1206TD-1.75A	1.75			0.18	0.20	0.450	E
1206TD-2A	2.00			0.135	0.41	0.316	N
1206TD-2.5A	2.50			0.075	0.68	0.240	O
1206TD-3A	3.00			0.047	1.5	0.187	P
1206TD-3.5A	3.50			0.038	2.0	0.180	R
1206TD-4A	4.00	50A @ 32Vdc 300A @ 24Vdc		0.034	2.5	0.173	S
1206TD-4.5A	4.50			0.029	2.65	0.164	X
1206TD-5A	5.00			0.024	4	0.145	T
1206TD-6A	6.00			0.016	12	0.140	F
1206TD-7A	7.00			0.0123	14	0.130	7
1206TD-8A	8.00	150A @ 32Vdc 300A @ 24Vdc		0.0083	16	0.123	M
1206TD-10A	10.0			0.0065	22	0.110	U
1206TD-12A	12.0			0.0050	11.5	0.085	12
1206TD-15A	15.0			0.0037	16.5	0.078	15
1206TD-20A	20.0			0.0034	50	0.080	Q
1206TD-25A	25.0			0.0016	60	0.090	L
1206TD-30A	30.0			0.0013	100	0.090	Z

Time Delay | 0.126x0.064 inch

Thick Film Chip Fuses

1206TD Series

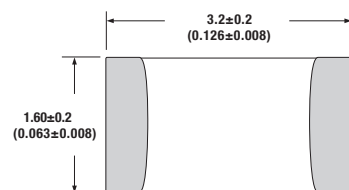
Part Number	Ampere Rating (A)	Interrupting Rating	Voltage Rating	Typical Cold Resistance (Ohms)	Typical Melting I ² t (A ² Sec)	Typical Voltage Drop (V)	Marking Code
1206TD-40A	40	200A @ 32Vdc		0.00085	240	0.095	XL
1206TD-50A	50	200A @ 24Vdc		0.00070	260	0.095	50

Note:

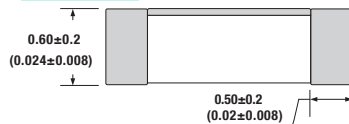
1. DC Interrupting Rating (Measured at rated voltage, time constant of less than 50 microseconds, battery source)
2. DC Cold Resistance are measured at <10% of rated current in ambient temperature of 25 °C
3. Typical Pre-arcing I²t are measured at 10In Current

Dimension

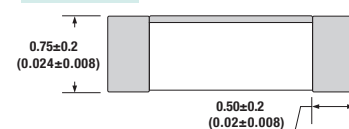
Unit: mm/inch



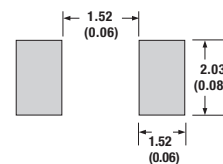
630mA-30A



40A-50A



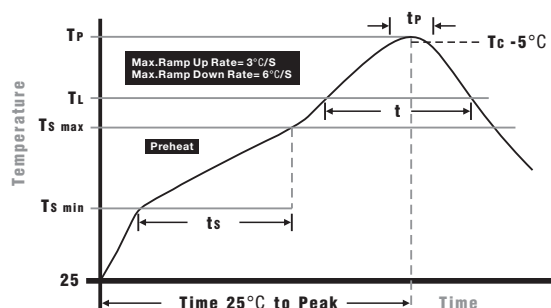
Pad layout



Packaging

- Quantity: 3,000pcs
- 8mm wide tape on 178mm(7 inch) diameter reel -specification EIA Standard 481.

Soldering Parameters



Wave Soldering: 260°C, 10 seconds max.
Infrared Reflow: 260°C, 30 seconds max.

IR Reflow Profile

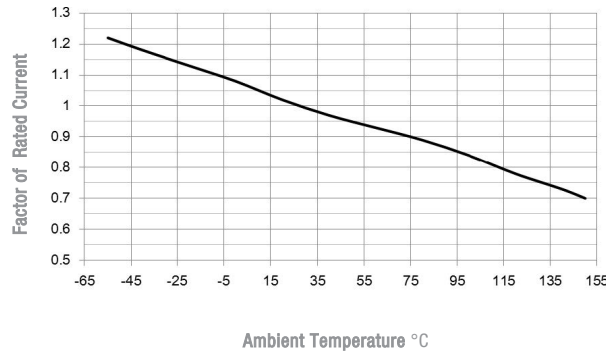
Preheat Heat	
Temperature min (T _{min})	150°C
Temperature max(T _{max})	200°C
Time (T _{min} to T _{max}) (ts)	60 - 120 seconds
Average ramp-up rate (T _{max} to T _p)	3°C/second max.
Liquidous temperature (T_L)	217°C
Time at liquidous (t _L)	60 - 150 seconds
Peak temperature(T_p)	260+0/-5°C
Time within 5°C of actual peak Temperature (tp)	10 - 30 seconds
Average ramp-down rate (T _p to T _{max})	6°C/second max.
Time 25 °C to peak temperature	8 minutes max.

Time Delay | 0.126x0.064 inch

Thick Film Chip Fuses

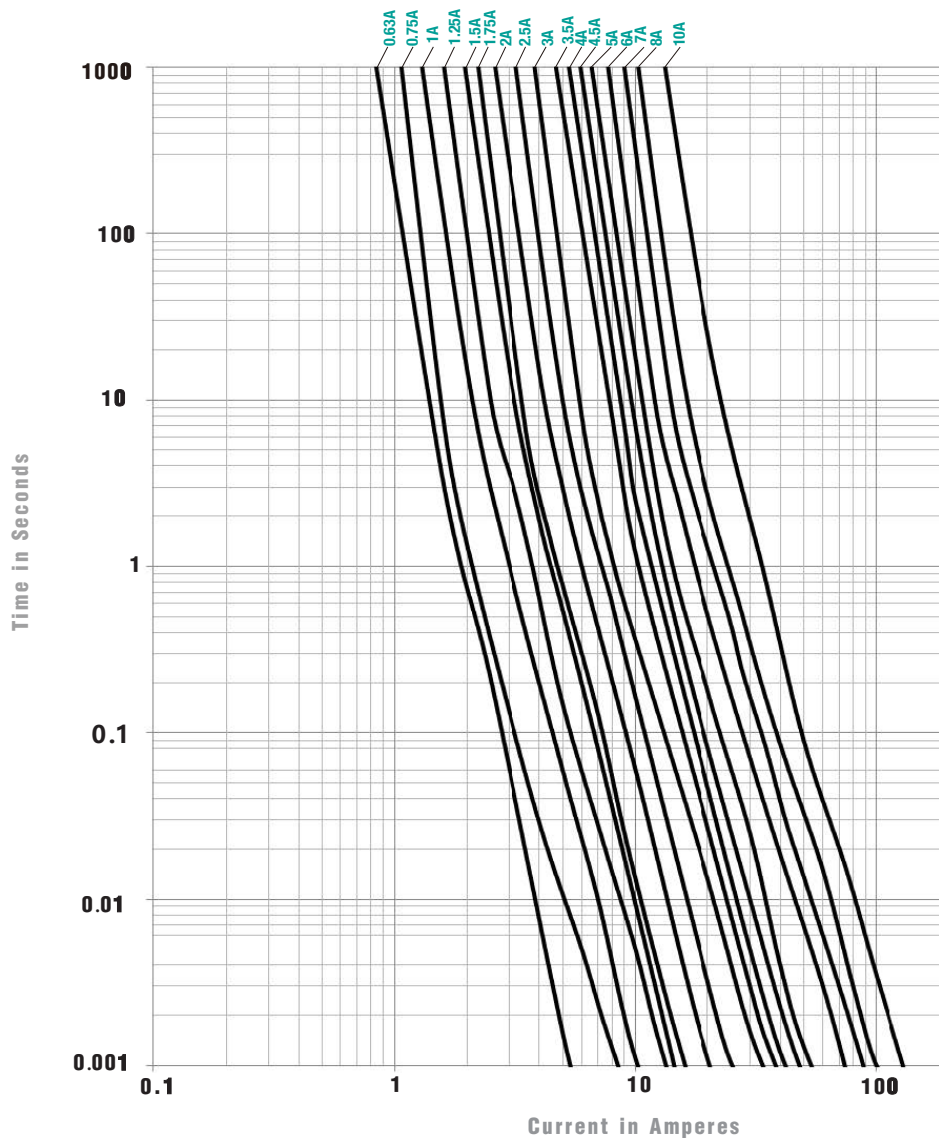
1206TD Series

Temperature Derating Curve



- Normal ambient temperature: 23+/-3 °C
- Operating temperature: -55 ~ 150 °C, with proper correction factor applied

Average Time Current Curves

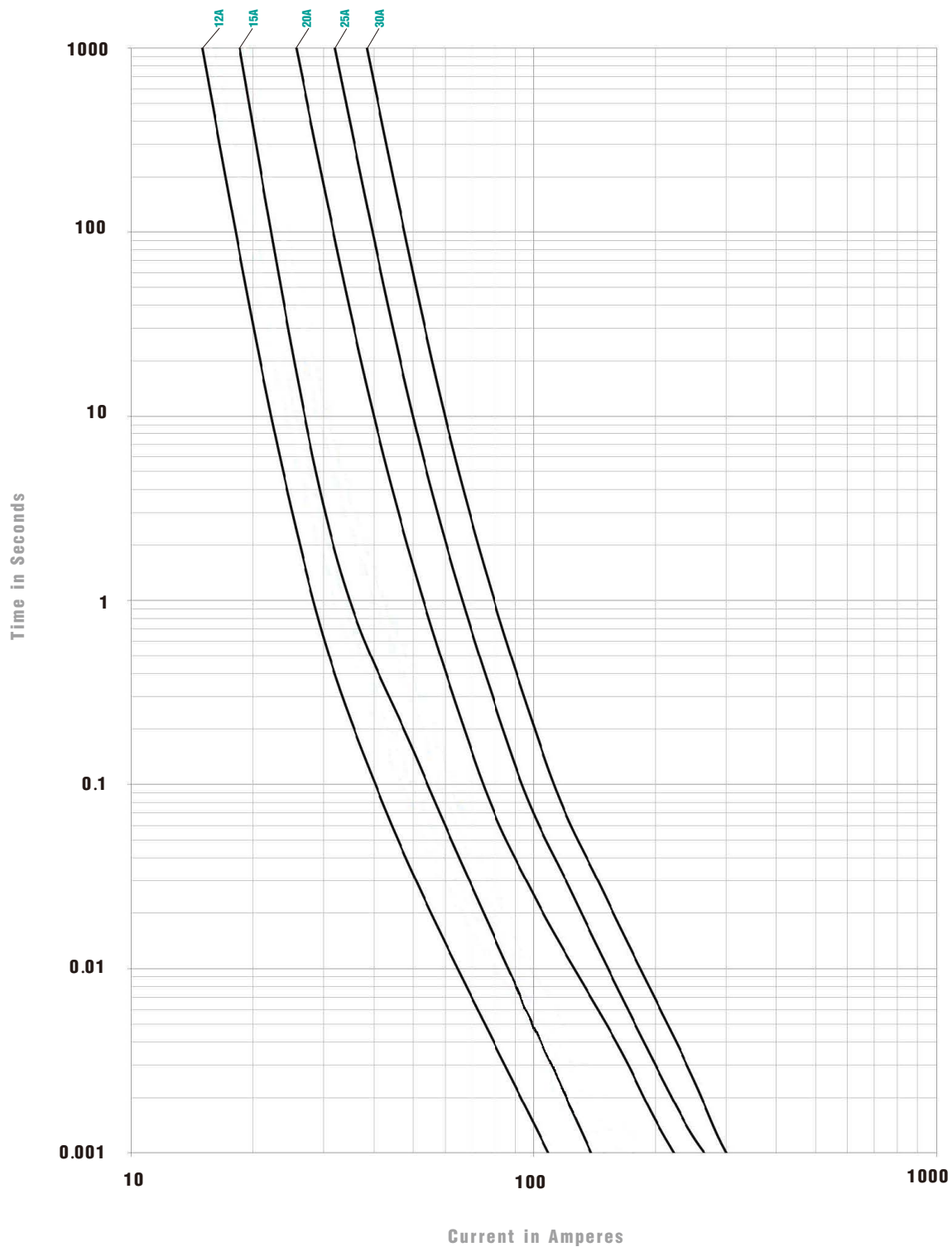


Time Delay | 0.126x0.064 inch

Thick Film Chip Fuses

1206TD Series

Average Time Current Curves



Time Delay | 0.126x0.064 inch

Thick Film Chip Fuses

1206TD Series

